Power LDMOS transistor

Rev. 3 — 12 January 2023

AMPLEON Product data sheet

## 1. Product profile

## 1.1 General description

This 13.6 V 25 W device is designed for land mobile radio (LMR) applications supporting the frequency range from HF up to 941 MHz.

### Table 1. Application performance

Typical RF performance at  $T_{case} = 25 \ ^{\circ}C$ ;  $V_{DS} = 13.6 \ V$ ; in a class-AB demo circuit.

Test signal	f	I <sub>Dq</sub>	P <sub>L(AV)</sub>	G <sub>p</sub>	η <sub>D</sub>	RL <sub>in</sub>
	(MHz)	(mA)	(W)	(dB)	(%)	(dB)
CW	380 to 460	42	31	>16.5	>49.0	-7.3
	520	45	25	18.4	72.0	–15
	740 to 800	100	25	>15.7	>61.5	-5.7
	800 to 870	100	25	>14.2	>64.7	-5.3

## **1.2 Features and benefits**

- High efficiency
- Integrated dual sided ESD protection
- Extreme ruggedness 65 : 1
- High power gain
- Excellent reliability
- Wideband
- High linearity
- For RoHS compliance see the product details on the Ampleon website

## 1.3 Applications

- TETRA, SSB and LTE mobile radio applications in VHF and UHF bands
- Wideband radio application, frequency range from 380 MHz to 460 MHz and from 800 MHz to 870 MHz

## 2. Pinning information

5S (TO-270-2F-1)	· · · ·	
drain	Ž	
gate		1 لــــا
source		
		3 sym112
5SG (TO-270-2G-1)		-
drain	2	
gate		1 لـــا
source		2
	1	sym112
	Source SSG (TO-270-2G-1) drain gate	gate source

[1] Connected to flange.

## 3. Ordering information

#### Table 3.Ordering information

Package name	Orderable part number	12NC	Packing description	Min. orderable quantity (pieces)
TO-270-2F-1	BLP9LA25SZ	9349 602 91515	TR13; 500-fold; 24 mm; dry pack	500
	BLP9LA25SXY	9349 602 91538	TR7; 100-fold; 24 mm; dry pack	100
TO-270-2G-1	BLP9LA25SGZ	9349 603 15515	TR13; 500-fold; 24 mm; dry pack	500
	BLP9LA25SGXY	9349 603 15538	TR7; 100-fold; 24 mm; dry pack	100

## 4. Limiting values

#### Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage		-	40	V
V <sub>GS</sub>	gate-source voltage		-5	+13	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature	[1]	-	225	°C

[1] Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

## 5. Thermal characteristics

Table 5.	Thermal characteristics					
Symbol	Parameter	Conditions	Тур	Unit		
R <sub>th(j-c)</sub>	thermal resistance from junction to case	$T_{case} = 80 \ ^{\circ}C; V_{DS} = 13.6 \ V;$ PL = 25 W	0.6	K/W		

### 6. Characteristics

#### Table 6.DC characteristics

 $T_i = 25 \ ^{\circ}C$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 1.0 \text{ mA}$	40	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 100 mA	1.5	2.0	2.5	V
I <sub>DSS</sub>	drain leakage current	$V_{GS} = 0 V; V_{DS} = 13.6 V$	-	-	1.4	μA
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 V;$ $V_{DS} = 10 V$	-	19	-	A
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	140	nA
<b>g</b> <sub>fs</sub>	forward transconductance	$V_{DS} = 10 \text{ V}; \text{ I}_{D} = 100 \text{ mA}$	-	0.93	-	S
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 V;$ I <sub>D</sub> = 3.5 A	-	128	-	mΩ

### Table 7. AC characteristics

 $T_j = 25 \ ^{\circ}C$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C <sub>iss</sub>	input capacitance	$V_{GS} = 0 V; V_{DS} = 13.6 V; f = 1 MHz$	-	96.9	-	pF
C <sub>oss</sub>	output capacitance	$V_{GS} = 0 V; V_{DS} = 13.6 V; f = 1 MHz$	-	50.6	-	pF
C <sub>rss</sub>	reverse transfer capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 13.6 V; f = 1 MHz	-	0.86	-	pF

#### Table 8. RF characteristics

Test signal: CW at  $V_{DS}$  = 13.6 V:  $I_{Dq}$  = 45 mA;  $T_{case}$  = 25 °C; unless otherwise specified; in a class-AB production circuit measured at frequencies of 520 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
G <sub>p</sub>	power gain	P <sub>L</sub> = 25 W	17.8	18.8	-	dB
RL <sub>in</sub>	input return loss	P <sub>L</sub> = 25 W	-	-18	-	dB
η <sub>D</sub>	drain efficiency	P <sub>L</sub> = 25 W	68	72	-	%

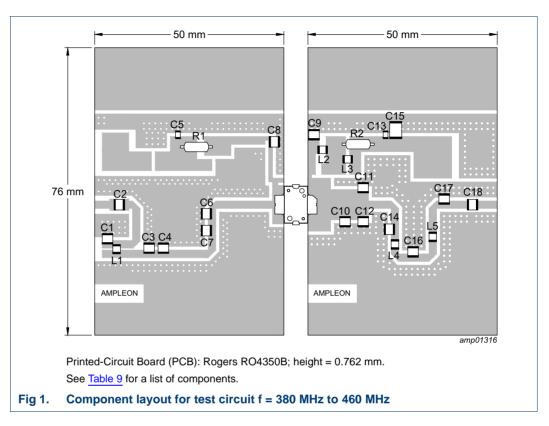
## 7. Test information

### 7.1 Ruggedness in class-AB operation

The BLP9LA25S and BLP9LA25SG are capable of withstanding a load mismatch corresponding to VSWR = 65 : 1 through all phases under the following conditions:  $V_{DS} = 13.6 \text{ V}$ ;  $I_{Dq} = 45 \text{ mA}$ ;  $P_L = 25 \text{ W}$  (CW); f = 520 MHz.

### 7.2 Test circuit

### 7.2.1 Test circuit f = 380 MHz to 460 MHz



### Table 9.List of components

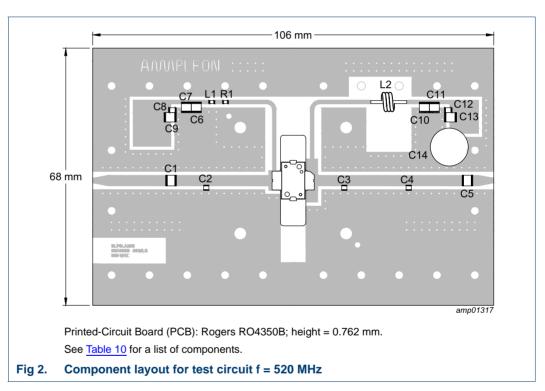
#### See <u>Figure 1</u> for component layout.

Component	Description	Value	Remarks
C1	multilayer ceramic chip capacitor	9.1 pF	ATC 100B
C2	multilayer ceramic chip capacitor	100 pF	ATC 100B
C3	multilayer ceramic chip capacitor	6.8 pF	ATC 100B
C4	multilayer ceramic chip capacitor	15 pF	ATC 100B
C5	multilayer ceramic chip capacitor	100 nF, 50 V	
C6	multilayer ceramic chip capacitor	33 pF	ATC 100B
C7	multilayer ceramic chip capacitor	16 pF	ATC 100B
C8	multilayer ceramic chip capacitor	120 pF	ATC 100B
C9	multilayer ceramic chip capacitor	22 pF	ATC 100B
C10	multilayer ceramic chip capacitor	56 pF	ATC 100B
C11	multilayer ceramic chip capacitor	15 pF	ATC 100B
C12	multilayer ceramic chip capacitor	62 pF	ATC 100B
C13	multilayer ceramic chip capacitor	100 nF, 50 V	
C14	multilayer ceramic chip capacitor	27 pF	ATC 100B
C15	multilayer ceramic chip capacitor	4.7 μF	
C16	multilayer ceramic chip capacitor	6.8 pF	ATC 100B

#### Table 9. List of components ...continued

See <u>Figure 1</u> for component layout.					
Component	Description	Value	Remarks		
C17	multilayer ceramic chip capacitor	1.7 pF	ATC 100B		
C18	multilayer ceramic chip capacitor	100 pF	ATC 100B		
L1	inductor air core	~6.9 nH			
L2	inductor air core	~23 nH			
L3	inductor air core	~22 nH			
L4, L5	wire one turn	~0.4 nH			
R1	axial resistor	68 Ω			
R2	axial resistor	49 Ω			

### 7.2.2 Test circuit f = 520 MHz



#### Table 10.List of components

See Figure 2 for component layout.

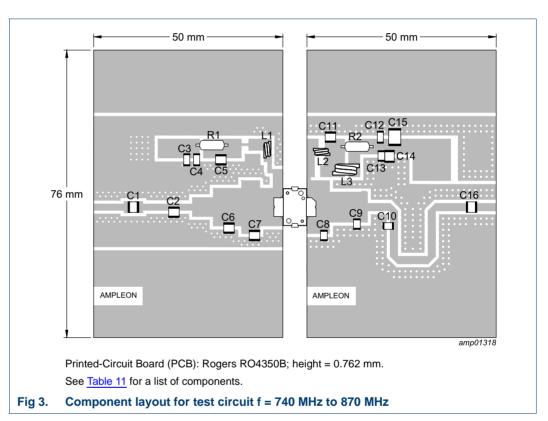
Component	Description	Value	Remarks
C1	multilayer ceramic chip capacitor	11 pF	ATC 100B
C2	multilayer ceramic chip capacitor	24 pF	ATC 600F
C3	multilayer ceramic chip capacitor	24 pF	ATC 600F
C4	multilayer ceramic chip capacitor	10 pF	ATC 600F
C5	multilayer ceramic chip capacitor	15 pF	ATC 100B
C6, C10	multilayer ceramic chip capacitor	22 pF	ATC 100B
C7, C11	multilayer ceramic chip capacitor	1 nF	ATC 100B
C8, C12	multilayer ceramic chip capacitor	0.1 μF	GRM21BR71H104KA01L

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## Table 10. List of components ...continued See Figure 2 for component location

See <u>Figure 2</u> for component layout.					
Component	Description	Value	Remarks		
C9, C13	multilayer ceramic chip capacitor	1 μF	GRM32RR71H105KA01L		
C14	electrolytic capacitor	1000 μF, 63 V			
L1	wire wound inductor	43 nH	LQW18AN43NG80		
L2	inductor air core	~53 nH			
R1	SMD	10 Ω			

#### 7.2.3 Test circuit f = 740 MHz to 800 MHz and f = 800 MHz to 870 MHz



### Table 11. List of components

#### See Figure 3 for component layout.

Component	Description	Value	Remarks
C1	multilayer ceramic chip capacitor	47 pF	ATC 100B
C2	multilayer ceramic chip capacitor	10 pF	ATC 100B
C3	multilayer ceramic chip capacitor	1 μF	GRM31MR71E105KA01L
C4	multilayer ceramic chip capacitor	100 nF	C1206C104K1RAC
C5	multilayer ceramic chip capacitor	220 pF	ATC 100B
C6	multilayer ceramic chip capacitor	8.2 pF	ATC 100B
C7	multilayer ceramic chip capacitor	18 pF	ATC 100B
C8	multilayer ceramic chip capacitor	18 pF	ATC 800B
C9	multilayer ceramic chip capacitor	16 pF	ATC 800B

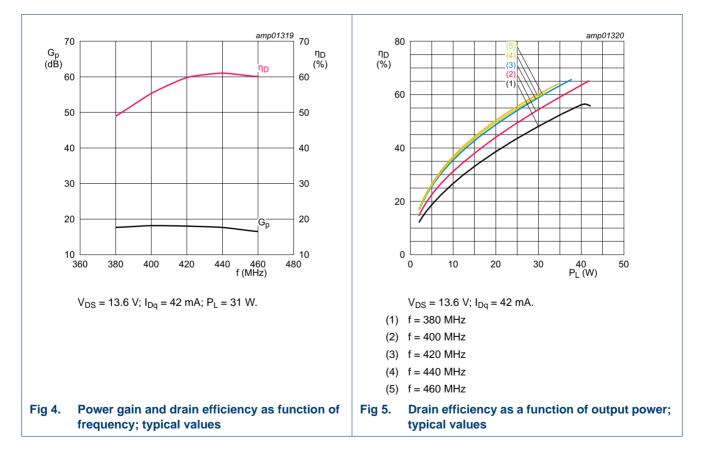
#### Table 11. List of components ...continued

See Figure 3 for component layout.

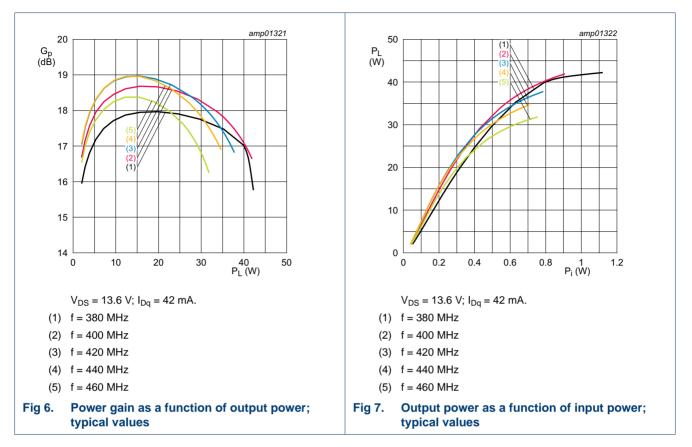
Component	Description	Value	Remarks
C10	multilayer ceramic chip capacitor	8.2 pF	ATC 800B
C11	multilayer ceramic chip capacitor	100 pF	ATC 100B
C12	multilayer ceramic chip capacitor	100 nF	C1206C104K1RAC
C13	multilayer ceramic chip capacitor	1 nF	ATC 100B
C14	multilayer ceramic chip capacitor	1 μF	GRM32RR71H105KA01L
C15	multilayer ceramic chip capacitor	10 μF, 50 V	
C16	multilayer ceramic chip capacitor	82 pF	ATC 800B
L1	inductor air core	~5 nH	
L2	inductor air core	~9 nH	
L3	inductor air core	~15 nH	
R1	axial resistor	68 Ω	
R2	axial resistor	10 Ω	

### 7.3 Graphical data

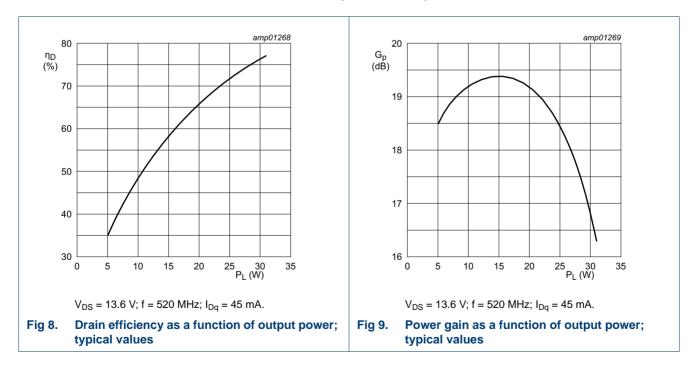
### 7.3.1 1-Tone CW measurements (f = 380 MHz to 460 MHz)



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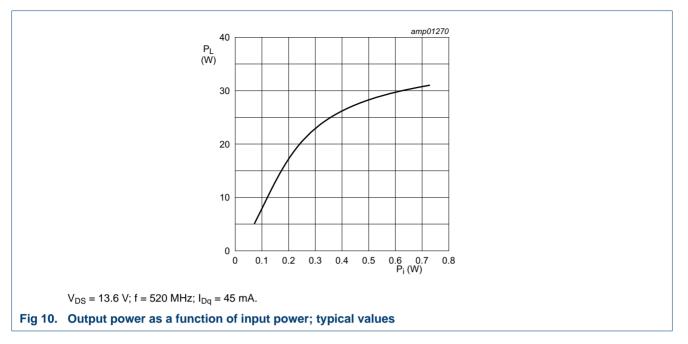
#### 7.3.2 1-Tone CW measurements (f = 520 MHz)



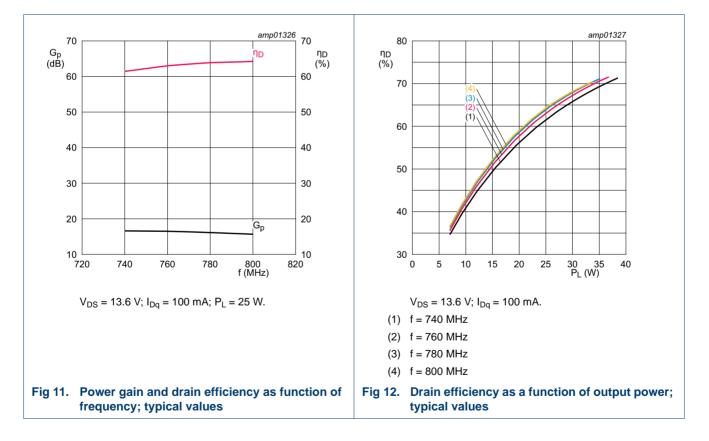
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# **BLP9LA25S: BLP9LA25SG**

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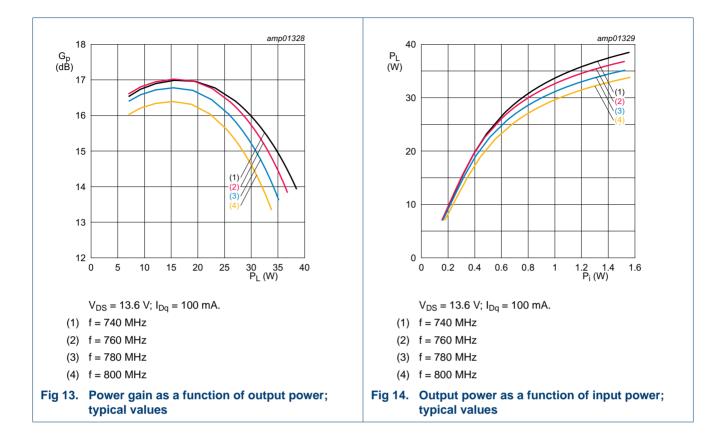
### 7.3.3 1-Tone CW measurements (f = 740 MHz to 800 MHz)

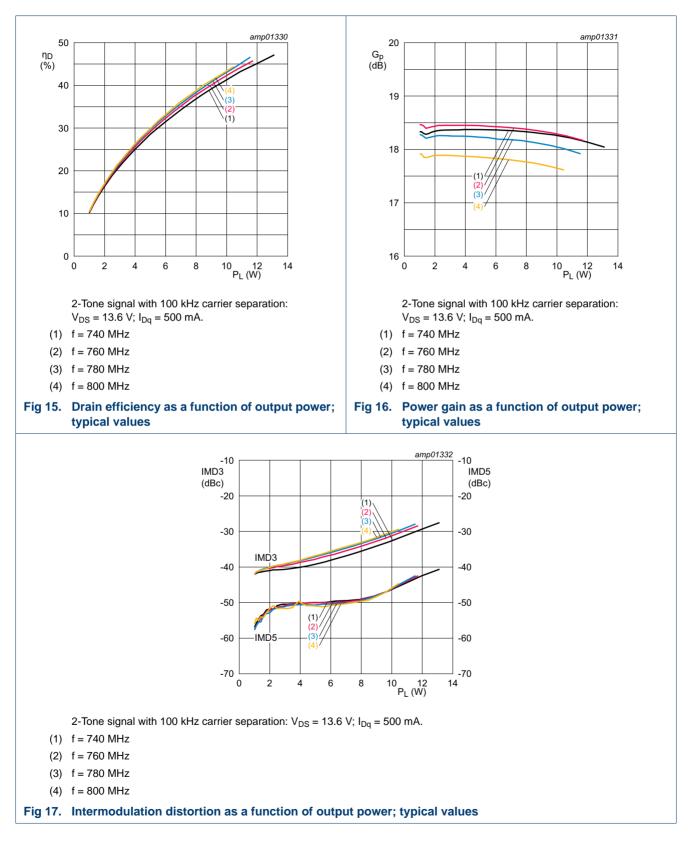


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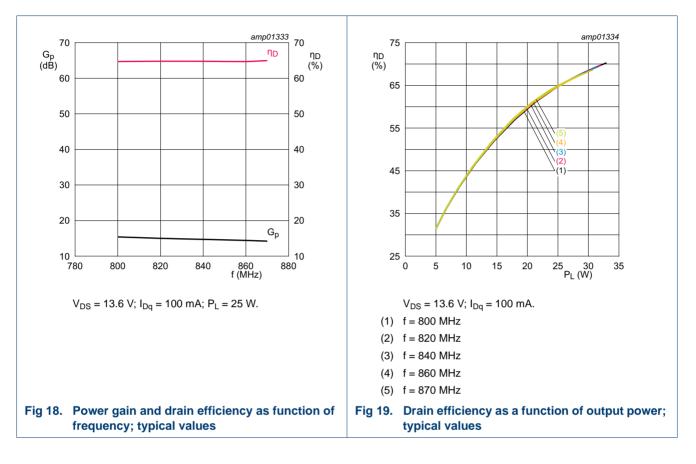
# **BLP9LA25S: BLP9LA25SG**

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### 7.3.4 2-Tone CW measurements (f = 740 MHz to 800 MHz)

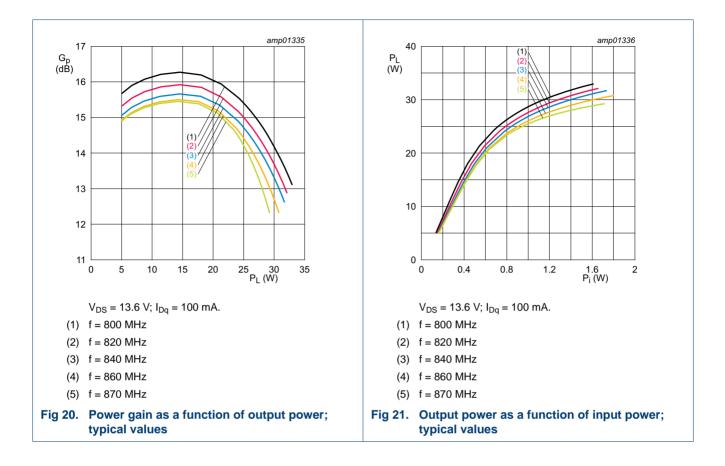


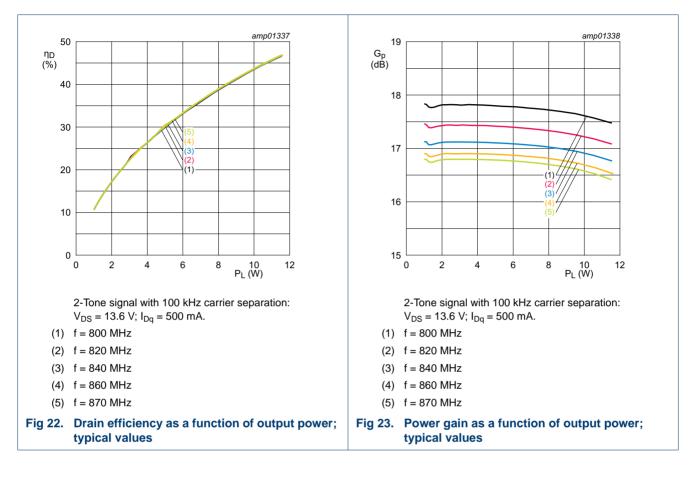
### 7.3.5 1-Tone CW measurements (f = 800 MHz to 870 MHz)

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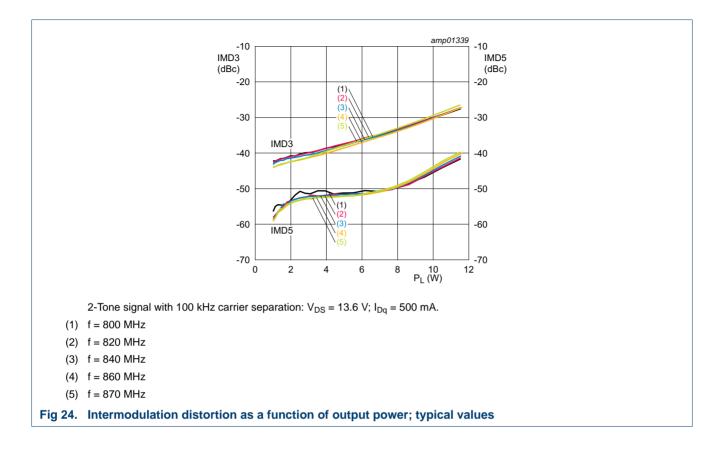


### 7.3.6 2-Tone CW measurements (f = 800 MHz to 870 MHz)

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## 8. Package outline

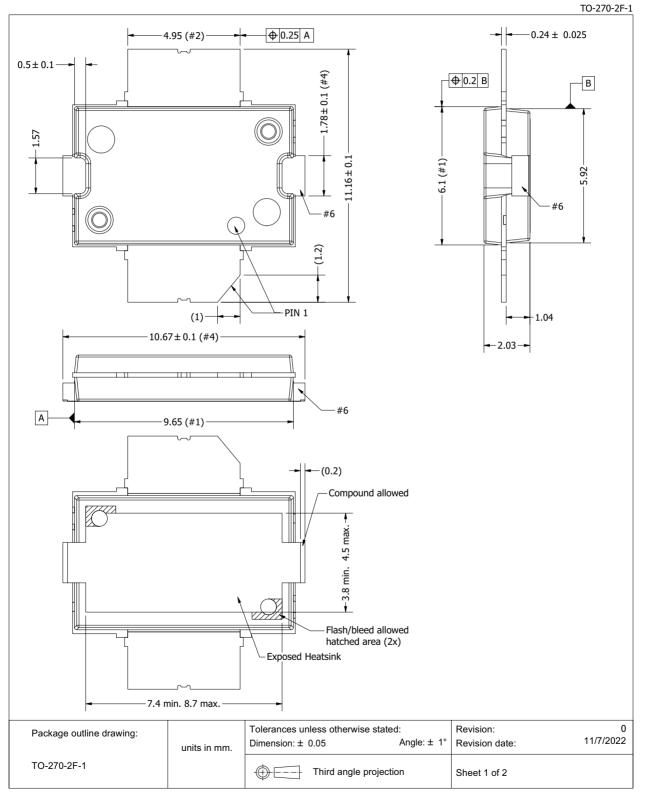


Fig 25. Package outline TO-270-2F-1 (sheet 1 of 2)

**Product data sheet** 

**Power LDMOS transistor** 

TO-270-2F-1

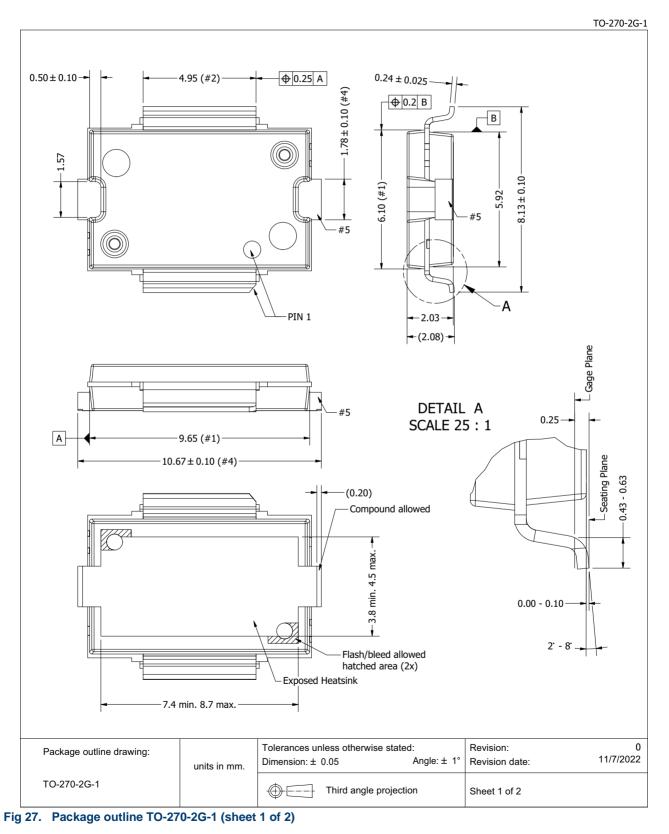
			Drawing Notes		
Items			Description		
(1)	Dimensions are exc	cluding mold protru	usion. The mold protrusion is maximum 0.15 mm p	per side. See also detail B.	
( )	In the dambar area	max. protrusion is	6 0.55 mm. max. in length and 0.3 mm. max. in with	dth (4x). See also detail B.	
(2)	The lead dambar (r	The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.			
(3)	The leads and expo	osed heatsink are	plated with matte Tin (Sn).		
(4)		Dimensions (Heatsink ears) 10,67 and 1,78 do not include mouldprotrusion. Overall Max. dimensions incl. mould			
	protrusions is 10.92				
(5)	Lead coplanarity ov				
(6)	Surfaces may rema	in unplated (not so	olderable surfaces).		
A CONTRACTOR					
	B	Lead Dar	(0.3 max.) (0.5 max.) mbar protrusion (#2)	DETAIL B SCALE 50 : 1	
°ackage o	utline drawing:	Lead Dar	(0.55 max)	SCALE 50 : 1	

#### Fig 26. Package outline TO-270-2F-1 (sheet 2 of 2)

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**Power LDMOS transistor** 



**Power LDMOS transistor** 

TO-270-2G-1

			Drawing Notes	
Items			Description	
	Dimensions are exc	luding mold protru	ision. The mold protrusion is maximum 0.15 mm p	per side. See also detail B.
(1)	In the dambar area	max. protrusion is	0.55mm max. in lenght and 0.3 mm max. in width	n (4x) See also detail B.
(2)	The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.			
(3)	The leads and exposed heatsink are plated with matte Tin (Sn).			
	Dimensions (Heatsink ears) 10,67 and 1,78 do not include mouldprotrusion. Overall Max. dimensions incl. mould			
(4)	protrusions is 10,92 mm. (max.) and 2,03 mm. (max.).			
(5)	Surfaces may rema	in unplated (not so	olderable surfaces).	
B-				DETAIL B CALE 50 : 1
				5 max. (#1)
Package of	Itline drawing:			Revision: Revision date: 11/7/2

#### Fig 28. Package outline TO-270-2G-1 (sheet 2 of 2)

BLP9LA25S\_BLP9LA25SG

## 9. Handling information

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

#### Table 12.ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

[1] CDM classification C2A is granted to any part that passes after exposure to an ESD pulse of 500 V.

[2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V.

### **10. Abbreviations**

Table 13. Abbreviations	3
Acronym	Description
CW	Continuous Wave
ESD	ElectroStatic Discharge
HF	High Frequency
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
LTE	Long Term Evolution
MTF	Median Time to Failure
RoHS	Restriction of Hazardous Substances
SSB	Single Side-Band
SMD	Surface Mounted Device
TETRA	TErrestrial Trunked Radio
UHF	Ultra High Frequency
VHF	Very High Frequency
VSWR	Voltage Standing Wave Ratio

## 11. Revision history

### Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLP9LA25S_BLP9LA25SG v.3	20230112	Product data sheet	-	BLP9LA25S_BLP9LA25SG v.2
Modifications:		page 2: package nam 483-1 to TO-270-2G-		SOT1482-1 to TO-270-2F-1 and
		page 2: package nam 483-1 to TO-270-2G-		SOT1482-1 to TO-270-2F-1 and
	• Table 5 on	page 3: value change	d from 0.932 K/W	to 0.6 K/W
		on page 16: package of -1 and from SOT1483		anged from SOT1482-1 to 1
	Section 12	on page 22: updated	section	
BLP9LA25S_BLP9LA25SG v.2	20210716	Product data sheet	-	BLP9LA25S_BLP9LA25SG v.1
BLP9LA25S_BLP9LA25SG v.1	20200616	Product data sheet	-	-

## 12. Legal information

### **12.1** Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.ampleon.com.

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## 14. Contents

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